

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10511566			
<b>Filing Date:</b>	13-Apr-2005			
<b>Title of Invention:</b>	Method for forming housings for electronic components and electronic components that are hermetically encapsulated thereby			
<b>First Named Inventor/Applicant Name:</b>	Jurgen Leib			
<b>Filer:</b>	Charles Nicholas Ruggiero/ruth olivo			
<b>Attorney Docket Number:</b>	2133.063USU			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
Independent claims in excess of 3	1614	1	220	220
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension - 3 months with \$0 paid	1253	1	1110	1110
<b>Miscellaneous:</b>				
Request for continued examination	1801	1	810	810
<b>Total in USD (\$)</b>				<b>2140</b>